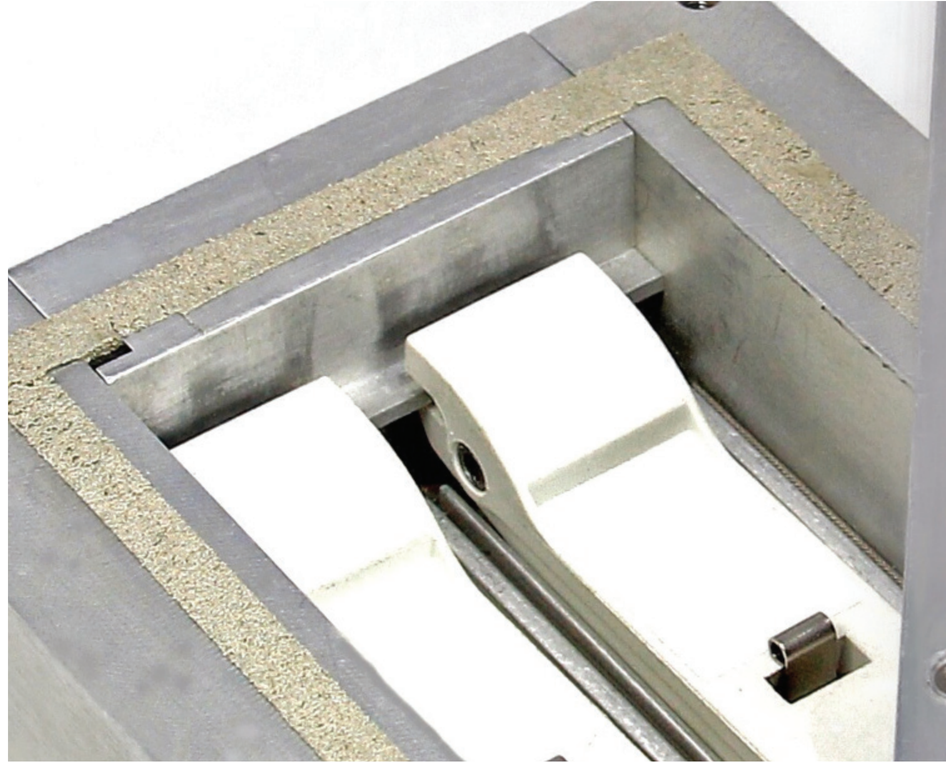
CHO-BOND 360-20

TWO COMPONENT GENERAL PURPOSE ELECTRICALLY CONDUCTIVE EPOXY ADHESIVE

Customer Value Proposition:

CHO-BOND 360-20 is a two-component, silver plated copper filled conductive epoxy adhesive designed for applications where a strong, conductive electrical bond must be achieved. The silver copper filler of CHO-BOND 360-20 provides a cost effective alternative to pure silver filled conductive epoxies in applications where moderate conductivity is acceptable. This thick paste is good for filling rather large bond lines and cracks (0.004 inches -0.025 inches) of electrical boxes and enclosures.

Curing of CHO-BOND 360-20 can be achieved in as little as 15 minutes with heat to minimize equipment downtime and increase manufacturing throughput. The 1:1 weight mix ratio makes CHO-BOND 360-20 easy to handle and use. Typical applications include poorly tolerance enclosures or castings, EMI vents and windows, and vertical and overhead fillet applications.



Features and Benefits:

• Two component	• Fast heat cure, increases throughput, minimizes equipment downtime.
• Silver-plated copper filler	• Low cost ($/cc), good conductivity 0.005 ohm-cm.
• Epoxy	• 60 minute working life, works well over wide temperature range, good chemical resistance >1600 psi lap shear, good for permanently bonding surfaces.
• Gritty paste	• Thick paste, good for relatively large cracks and voids (>0.25 in). Can be used on overhead or vertical surfaces
• No VOCs	• Minimal shrinkage, no permits or ventilation required.

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CHO-BOND 360-20 - Product Information

Table 1 Typical Properties

CHO-BOND 360-20			
Typical Properties	**Typical Values**	**Test Method**	
Polymer	Epoxy	N/A	
Filler	Silver-Plated Copper	N/A	
Mix Ratio, A : B (by weight)	1 : 1	N/A	
Color	Light Gray	N/A	(Q)
Consistency	Gritty Paste	N/A	(Q)
Maximum DC Volume Resistivity (Cure Cycle 1)	0.005 ohm-cm	CHO-95-40-5101*	(Q/C)
Minimum Lap Shear Strength (Cure Cycle 1)	1600 psi (11,032 kPa)	CHO-95-40-5300*	(Q/C)
Specific Gravity (Room Temp Cure)	5.0	ASTM D792	(Q/C)
Hardness (Cure Cycle 1)	80 Shore D	ASTM-D2240	(Q)
Continuous Use Temperature	- 62°C to 100°C (-80 °F to 212 °F)	N/A	(Q)
Elevated Temperature Cure Cycle	**Cure Cycle Option 1:** 0.25 hours @ 115°C (235°F) **Cure Cycle Option 2:** 2.0 hours @ 66°C (150°F)	N/A	
Room Temperature Cure	24 hours	N/A	(Q)
Working Life	1.0 hour	N/A	(Q)
Shelf Life, unopened	9 months @ 25°C (77°F)	N/A	(Q)
Minimum thickness recommended	0.010 in (0.25 mm)	N/A	
Maximum thickness recommended	None	N/A	
Volatile Organic Content (VOC)	0 g/l	Calculated	
Theoretical Coverage Area at 0.010" Thick per Pound (454 grams)	5,500 in^2 (35,484 cm^2)	N/A	

Note: N/A – Not Applicable, (Q/C) - Qualification and Conformance Test, (Q) - Qualification Test
* This test Method is available from Parker Chomerics.

Table 2 Ordering Information

Product	Weight (grams)	Packaging	Part Number	Primer Included
CHO-BOND 360-20	85	2 component, 1/2 pint aluminum can kit	50-00-0360-0020	Not Required
	454	2 component, 1 pint aluminum can kit	50-01-0360-0020	Not Required

Please refer to Parker Chomerics Surface Preparation and CHO-BOND Application documents for information regarding the proper surface preparation, primer application (if required), and use of these compounds.

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